



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/014,310
Filing Date December 11, 2001
Inventor Ritesh P. Shah, et al.
Assignee Honeywell International Inc.
Group Art Unit 1753
Examiner A. Oltmans
Attorney's Docket No. 32120-CON1
Title: Methods of Forming Metal Articles

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

RECEIVED
DEC 09 2003
TC 1700

Dated: 01 Dec 2003

By: _____

James E. Lake
Reg. No. 44,854

12/05/2003 YPOLITE1 00000004 10014310

02 FC:1806

180.00 OP

EL979977157

Form PTO-1400		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 32120-CON1		SERIAL NO. 10/014,310	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Ritesh P. Shah, et al.			
				FILING DATE December 11, 2001		GROUP 1753	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,844,746	07/1989	Hormann et al			
	AB	6,521,173	02/2003	Kumar			
	AC	6,454,994	09/2002	Wang			
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No
	AM	JP-H03-197640A	08/1991	Japan			
	AN	EP 0902102 A1	08/1998	EPO			
	AO	EP 0281141 B2	03/1988	EPO			
	AP	JP59227992A	12/1984	Japan			
	AQ						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR		"Nickel, Cobalt and Their Alloys", pub. By ASM International, December 2000, pages 76, 230-234.				
	AS		S. Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12 th International Plansee Seminar, 1989, Top 5: Ultrapure Refractory Metals, pgs. 207, 216.				
	AT		P. Ding et al, "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference 1997, ISMIC-107/97/0087(c), pgs. 87-92.				
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

EL979977157